查询2SJ681供应商 TOSHIBA

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

2SJ681

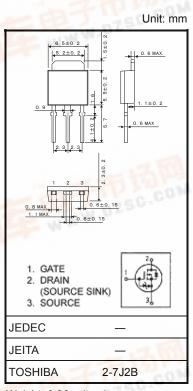
Relay Drive, DC–DC Converter and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance: R_{DS} (ON) = 0.12 Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0 \text{ S} (typ.)$
- Low leakage current: $I_{DSS} = -100 \ \mu A \ (max) \ (V_{DS} = -60 \ V)$
- Enhancement mode: $V_{th} = -0.8$ to -2.0 V

 $(V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		VDSS	-60	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		VDGR	-60	V	
Gate-source voltage	He ?	V _{GSS}	±20	V	
Drain current	DC (Note 1)	Ι _D	-5	A	
	Pulse(Note 1)	I _{DP}	-20	A	
Drain power dissipatio	n	PD	20	W	
Single pulse avalanche energy (Note 2)		E _{AS}	40.5	mJ	
Avalanche current		I _{AR}	-5	А	
Repetitive avalenche energy (Note 3)		E _{AR}	2	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 0.36 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = -25 \text{ V}, T_{ch} = 25^{\circ}\text{C}$ (initial), L = 2.2 mH, R_G = 25 Ω , I_{AR} = -5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





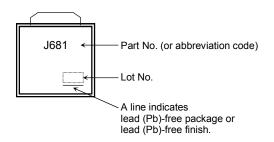
Electrical Characteristics (Ta = 25°C)

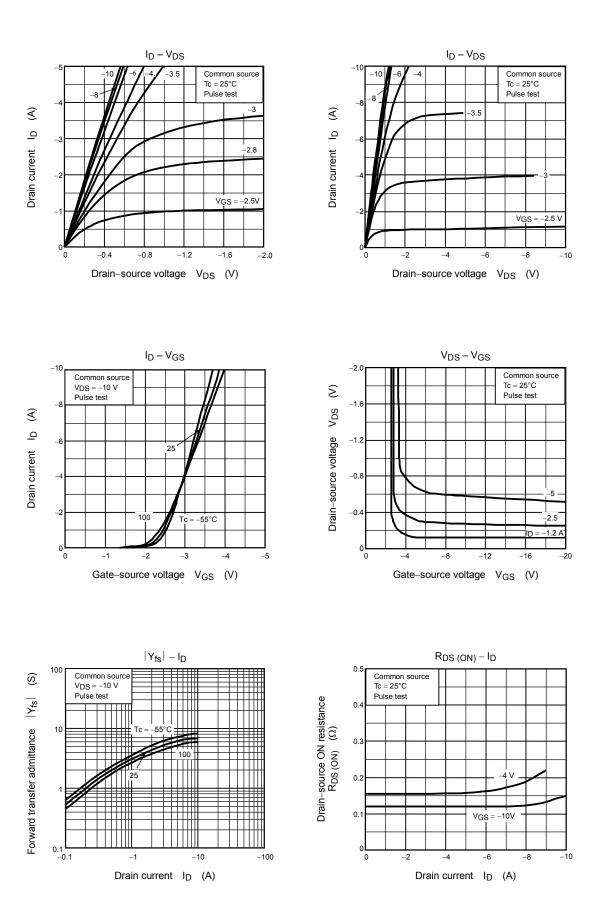
Charae	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	IGSS	V _{GS} = ±16 V, V _{DS} = 0 V	_	—	±10	μA
Drain cut-off cu	rrent	IDSS	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-100	μA
Drain-source breakdown voltage		V (BR) DSS	I _D = -10 mA, V _{GS} = 0 V	-60	_	_	V
		V (BR) DSX	I _D = -10 mA, V _{GS} = 20 V	-35	_	_	V
Gate threshold	voltage	V _{th}	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON resistance		Descusion	V _{GS} = -4 V, I _D = -2.5 A —		0.16	0.25	Ω
		R _{DS (ON)}	V _{GS} = -10 V, I _D = -2.5 A		0.12	0.17	
Forward transfe	r admittance	Y _{fs}	V _{DS} = -10 V, I _D = -2.5 A	2.5	5.0	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz		700	_	pF
Reverse transfer capacitance		C _{rss}			60	_	
Output capacitance		C _{oss}			90	_	
Switching time	Rise time	tr	V_{GS} -10 V C_{GS} -10 V C_{GS} $R_{L} =$ 12 Ω $V_{DD} \approx -30 V$	_	14	_	
	Turn-on time	t _{on}		_	24	_	ns
	Fall time	t _f			14	_	
	Turn-off time	t _{off}	Duty \leq 1%, t _w = 10 µs	_	95	—	
Total gate charge (Gate-source plus gate-drain)		Qg		_	15	_	nC
Gate-source charge		Q _{gs}	V _{DD} ≈ -48 V, V _{GS} = -10 V, I _D = -5 A	—	11	—	
Gate-drain ("miller") charge		Q _{gd}	1		4	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

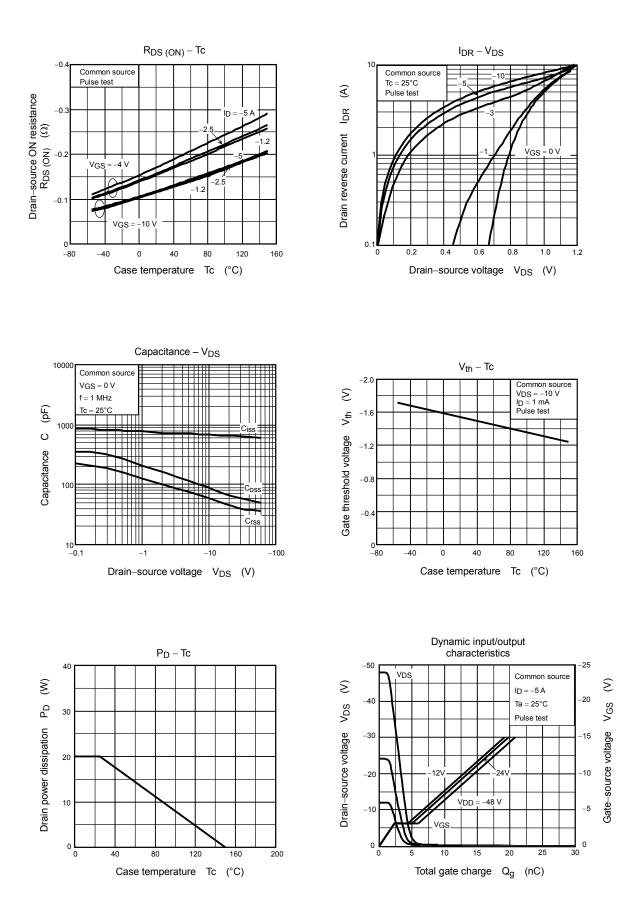
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	-5	А
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	-20	А
Forward voltage (diode)	V _{DSF}	I _{DR} = -5 A, V _{GS} = 0 V	_	_	1.7	V
Reverse recovery time	trr	I _{DR} = −5 A, V _{GS} = 0 V dI _{DR} / dt = 50 A / µS		40	_	ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 50 A / μS	_	32	_	nC

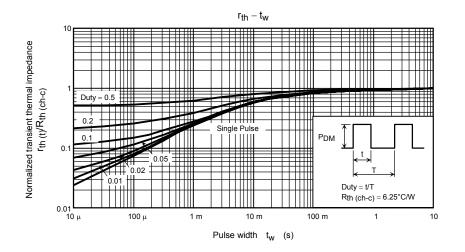
Marking

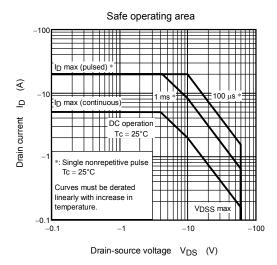


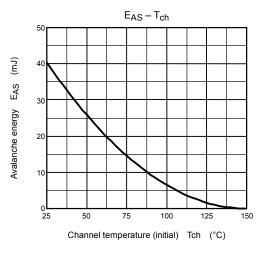


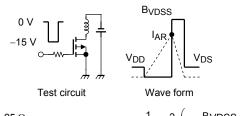
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